

5.0mm x 6.0mm SURFACE MOUNT LED LAMP

PRELIMINARY SPEC



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE

DEVICES

Part Number: AAAF5060QBDZGSEEC

Blue Green Hyper Red

Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

Description

The Blue source color devices are made with AlGaInN on Sapphire Light Emitting Diode.

The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

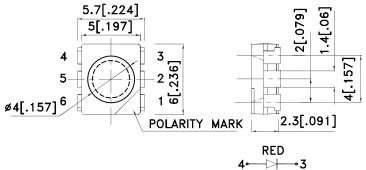
The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

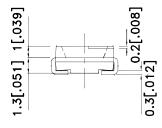
Static electricity and surge damage the LEDS.

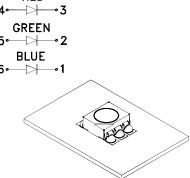
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 30mA *50mA		Viewing Angle [1]
			Min.	Тур.	201/2
AAAF5060QBDZGSEEC	Blue (AlGaInN)		110	250	100°
	Green (InGaN)	WATER CLEAR	280	650	
	Hyper Red (AlGalnP)		*650	*1000	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. *Luminous intensity with asterisk is measured at 50mA; Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue Green Hyper Red	468 515 630		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue Green Hyper Red	470 525 621		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue Green Hyper Red	25 30 20		nm	IF=20mA
С	Capacitance	Blue Green Hyper Red	100 45 25		pF	Vr=0V;f=1MHz
VF [2]	Forward Voltage	Blue Green Hyper Red	3.3 3.3 2	4 4.1 2.5	V	IF=20mA
lR	Reverse Current	Blue Green Hyper Red		10 10 10	uA	VR=5V

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

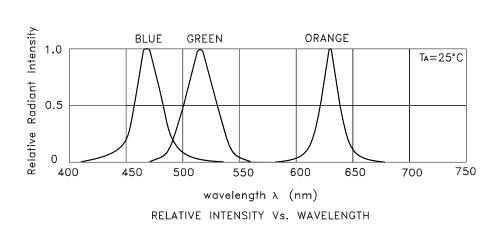
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Green	Hyper Red	Units			
Power dissipation[2]		mW					
DC Forward Current	30	30	50	mA			
Peak Forward Current [1]	150	150	195	mA			
Reverse Voltage		V					
Operating Temperature	-40°C To +85°C						
Storage Temperature	-40°C To +85°C						

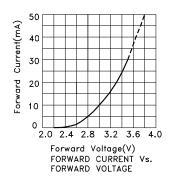
Notes:

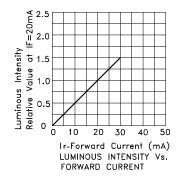
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. Within 350mW at all chips are lightened.

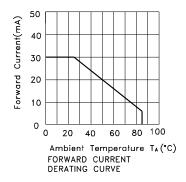
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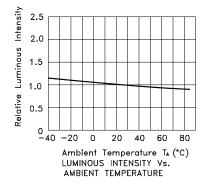


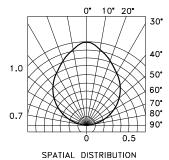
AAAF5060QBDZGSEEC Blue







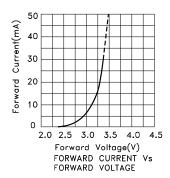


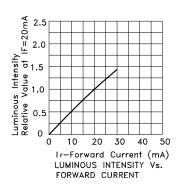


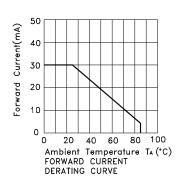
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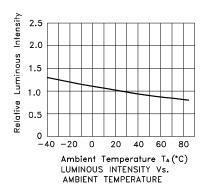
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Green



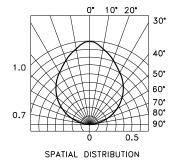






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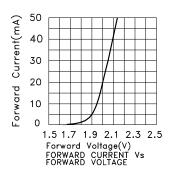
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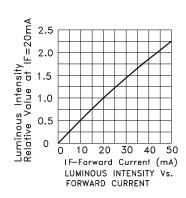


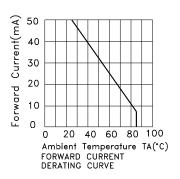
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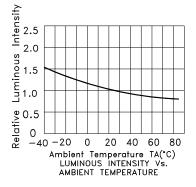
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Hyper Red



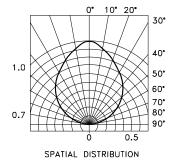






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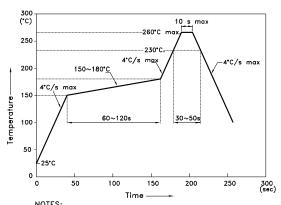
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AAAF5060QBDZGSEEC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



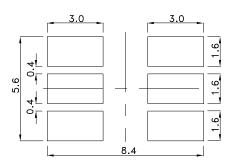
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

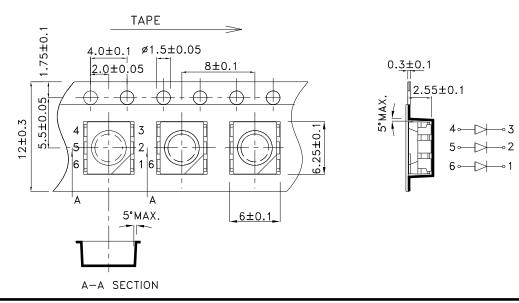
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



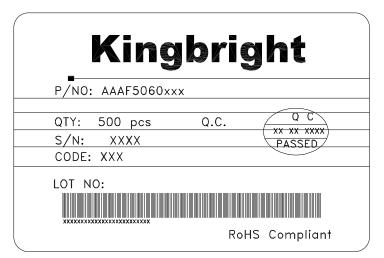
Tape Dimensions (Units: mm)



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PACKING & LABEL SPECIFICATIONS AAAF5060QBDZGSEEC USER DIRECTION OF FEED LABEL LABEL 500pcs / Reel 1 Reel / Bag OUTSIDE LABEL OUTSIDE LABEL Kingbright Kingbright 5K / 55# Box 10K / 56# BOX



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